

Description

The BSC097N06NS uses advanced trench technology

to provide excellent $R_{DS(ON)}$, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = 60V I_D =65A

 $R_{DS(ON)} < 11 m\Omega V_{GS} = 10V$

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

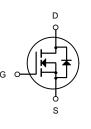
Product ID	Pack	Marking	Qty(PCS)
BSC097N06NS	DFN5X6-8L	097N06NS	5000

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	60	V
Vgs	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V	65	А
I _D @T _C =70°C	Continuous Drain Current, V _{GS} @ 10V	49	А
Ідм	Pulsed Drain Current ²	180	А
EAS	Single Pulse Avalanche Energy ³	56	mJ
P₀@Tc=25°C	Total Power Dissipation ⁴	89	W
Тѕтс	Storage Temperature Range -55 to 150		°C
TJ	Operating Junction Temperature Range -55 to 150		°C
R ₀ JA	Thermal Resistance Junction-Ambient ¹ 62		°C/W







N-Channel MOSFET



N-Channel Enhancement Mode MOSFET

Electrical Characteristics (TJ=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units	
			1		1		
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250µA	60	-	-	V	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V,	-	-	1.0	μA	
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	±100		nA	
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	1.0	1.6	2.5	V	
D	Static Drain-Source on-Resistance	V _{GS} =10V, I _D =20A	-	8	11		
$R_{DS(on)}$	note3	V _{GS} =4.5V, I _D =10A	-	14	20	mΩ	
Ciss	Input Capacitance		-	930	-	pF	
Coss	Output Capacitance	$V_{DS}=25V, V_{GS}=0V,$	_	370	-	pF	
Crss	Reverse Transfer Capacitance	f=1.0MHz	-	20	-	pF	
Qg	Total Gate Charge		-	19	-	nC	
Q _{gs}	Gate-Source Charge	$V_{DS}=30V, I_{D}=20A,$	-	4.8	-	nC	
Q_{gd}	Gate-Drain("Miller") Charge	V _{GS} =10V	-	4.5	-	nC	
t _{d(on)}	Turn-on Delay Time		-	4.9	-	ns	
tr	Turn-on Rise Time	V _{DD} =30V, I _D =20A,	-	31	-	ns	
t _{d(off)}	Turn-off Delay Time	R _G =1.6Ω, V _{GS} =10V	-	23	-	ns	
t _f	Turn-off Fall Time		-	8.7	-	ns	
	Maximum Continuous Drain to Source Diode Forward Current			-	65	А	
ls							
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	240	А	
N/	Drain to Source Diode Forward				1 1	V	
V_{SD}	Voltage	V _{GS} =0V, I _S =30A	-	-	1.4	V	
t _{rr}	Body Diode Reverse Recovery Time		-	34	-	ns	
Qrr	Body Diode Reverse Recovery	TJ=25℃,	-	14	-	nC	
	Charge	l⊧=20A,dl/dt=100A/µs					

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T_J=25 $^\circ \!\! C$, V_DD=30V, V_G=10V, R_G=25\Omega, L=0.5mH, I_{AS}=12A

3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



Typical Performance Characteristics

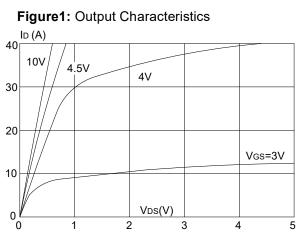
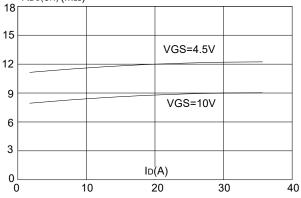
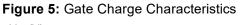
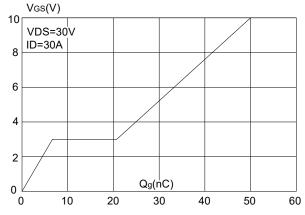


Figure 3:On-resistance vs. Drain Current $R_{DS(ON)}(m\Omega)$







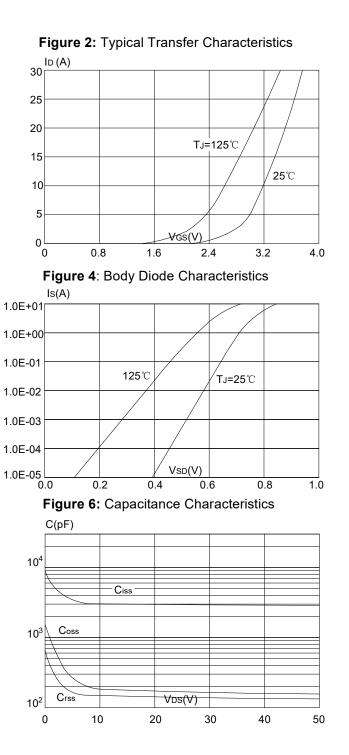




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

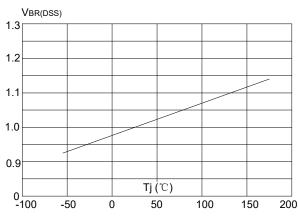


Figure 9: Maximum Safe Operating Area

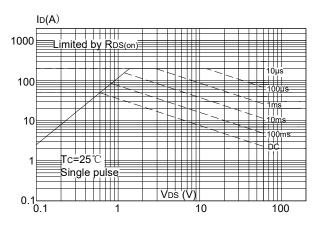


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

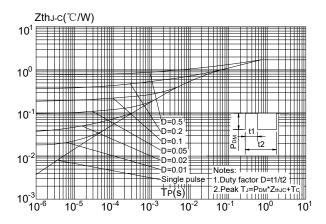


Figure 8: Normalized on Resistance vs. Junction Temperature

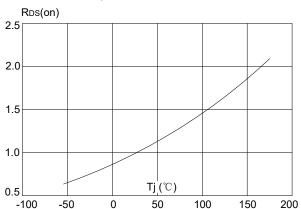
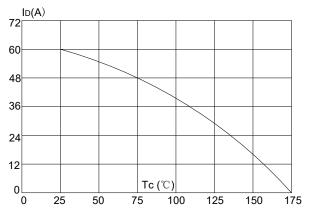
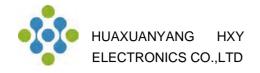


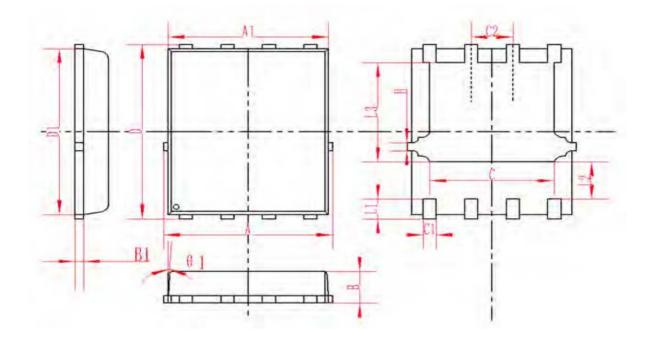
Figure 10: Maximum Continuous Drain Current vs. Case Temperature



N-Channel Enhancement Mode MOSFET



DFN5X6-8L Package Information



SYMBOL	MM		INCH			
	MIN	NOM	MAX	MIN	NOM	MAX
А	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
В	0.9	0.95	1	0.035	0.037	0.039
B1	0.254REF		0.010REF			
С	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2		1.27TYP			0.5TYP	
θ1	8°	10°	12°	8°	10°	12°
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
Н	0.24	0.25	0.26	0.009	0.010	0.010



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